

AMENDMENT TO THE CLAIMS:

Kindly replace the previous claim set with the claim set which appears below, in which Claims 13-14 and 37-39 have now been cancelled and Claims 1 and 19 have been amended to read as follows:

1. (Currently Amended) A thermal interface wafer for facilitating heat transfer from an electronic component to a heat sink when interposed therebetween, said wafer comprising at least one linear substrate having first and second surfaces with edges, said substrate having at least one layer of conformable, heat-conductive material formed upon a respective surface thereof, said heat-conductive material being formulated to enhance the heat transfer from said electronic component to said heat sink, wherein the wafer is formed from a cross-section having a shape selected from the group consisting of generally rectangular, generally circular, and generally square and said substrate is disposed to assume a substantially perpendicular orientation relative to the electronic component whereby the edges of said substrate contact the electronic component and the heat sink, wherein said heat-conductive material melts at a temperature from between approximately 50°C and 61°C.

2. (Original) The thermal interface wafer of claim 1 wherein said vertically-oriented planar substrate comprises a metallic layer.

3. (Original) The thermal interface wafer of claim 2 wherein said metallic layer is selected from the group consisting of copper, gold, silver and aluminum.

4. (Original) The thermal interface wafer of claim 1 wherein said planar substrate has a width no greater than about 0.2 inches.

5. (Original) The thermal interface wafer of claim 1 when said planar substrate has a width no greater than about 0.01 inches.

6. (Original) The thermal interface wafer of claim 1 wherein said planar substrate has a width from about 0.005 to 0.01 inches.

7. (Original) The thermal interface wafer of claim 1 wherein said substrate with conformable, heat-conducting material is formed as a coil.

Claim 8. (Cancelled)

9. (Original) The thermal interface wafer of claim 1 wherein said wafer is comprised of a multiplicity of vertically oriented planar substrates, each respective one of said substrates having said conformable, heat-conducting material formed upon a respective side thereof.

10. (Original) The thermal interface wafer of claim 9 wherein said wafer is comprised from a multiplicity of planar substrates with dedicated layers of conformable, heat-conducting material formed thereon.

11. (Original) The thermal interface wafer of claim 9 wherein said substrates with heat-conductive material formed thereon are arranged and generally parallel in relation to one another and compressibly bonded to one another.

Claim 12-18. (Cancelled)

19. (Currently Amended) A thermal interface for facilitating heat transfer from an electronic component to a heat sink comprising a multiplicity of elongate, vertically-oriented substrates, each respective substrate having at least

one layer of conformable, heat-conducting material formed thereon, said multiplicity of elongate strips being formed in generally parallel relation to one another to define a wafer interposable between said electronic component and said heat sink, wherein said thermal interface is formed from a cross-section having a shape selected from the group consisting of generally rectangular, generally circular and generally square, wherein said heat-conductive material melts at a temperature from between approximately 50°C and 61°C.

20. (Original) The thermal interface of claim 19 wherein said substrates are comprised of a metal foil selected from the group consisting of copper, gold, silver and aluminum.

Claims 21-39. (Cancelled)

AMENDMENT TO THE SPECIFICATION:

Please replace paragraph [0031] with the following paragraph:

[0031] Preferably, the thermally conductive composition may take any of those disclosed in Applicant's co-pending patent application entitled PHASE CHANGE THERMAL INTERFACE COMPOSITION HAVING INDUCED BONDING PROPERTY, filed on April 12, 2001, ~~Serial No. not yet assigned~~ Application No. 09/834,158 (now U.S. Patent No. 6,869,642), and Applicant's co-pending patent application entitled GRAPHITIC ALLOTROPE INTERFACE COMPOSITION AND METHOD OF FABRICATING THE SAME, filed on May 18, 2000, ~~and assigned~~ Application Serial No. 09/573,508 (now U.S. Patent No. 6,652,705), the teachings of which are expressly incorporated herein by reference. Such thermal compounds have the desirable phase-change properties of assuming a solid phase at normal room temperature, but liquify at elevated temperatures of approximately 51°C or higher, which is typically just below the operating temperatures at which most electronic components are intended to operate. The liquidation temperatures of approximately 51°C or higher are desirably 50°C to 61°C, which will thus correspond to the temperature at which the composition transitions from its solid phase to its molten

liquid phase. It should be understood, however, that a wide variety of alternative thermally conductive materials and compounds are available and readily known to those skilled in the art which could be deployed for use in the practice of the present invention.